



MATERIAL DATA FORM

Manufacturer contact Information

Contact Name	Compliance Coordinator
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Manufacturer's Part Number.	Total Mass of the Unit specified in (g):	Material Name	Substance Name	IMDS No.	Substance Mass (mg)	% Weight of Assembly	PPM of Total Assembly
DMP3098L-7	0.009	Die,Mosfet	Doped silicon	TBD	0.5108	5.70%	57008
Customer's Partnumber.		SOT-23 leadframe	CDA194	37507841	2.6309	29.36%	293650
			Die attached pad plating	37507916	0.1034	1.15%	11546
		Bonding wire	copper	TBD	0.1179	1.32%	13156
		Molding compound	CEL-1702HF-9	28644240	5.1353	57.32%	573185
		Die attach epoxy	84-1LMISR4	TBD	0.2055	2.29%	22942
		Tin solder	Pure Tin	37508652	0.2555	2.85%	28514
						Total (mg)	8.959



MATERIAL DATA FORM DETAIL

Manufacturer's Part Number.	Total Mass of the Unit specified in (g):	Material Name	Generic ID	Element	CAS No.	Substance Mass (mg)	% of Weight (Sub Assembly Material)	PPM of Sub Assembly Material	PPM of Total Weight
DMP3098L-7	0.009	Die,Mosfet	Doped silicon	Si	7440-21-3	0.5108	100.00%	1000000	57008
Customer's Partnumber.		SOT-23 leadframe	CDA194	Cu	7440-50-8	2.5625	97.40%	974000	286015
				Fe	1309-37-1	0.0631	2.40%	24000	7048
				P	7723-14-0	0.0021	0.08%	800	235
				Zn	7440-66-6	0.0032	0.12%	1200	352
			Pure silver	Ag	7440-22-4	0.1034	100.00%	1000000	11546
		Bonding wire	2.0mil	Cu	7440-50-8	0.1179	100.00%	1000000	13156
		Molding compound	CEL-1702HF-9	SiO2	60676-86-0	4.4832	87.30%	873000	500390
				Epoxy Resin	29690-82-2	0.2568	5.00%	50000	28659
				Phenol Resin	26834-02-6	0.2568	5.00%	50000	28659
				Aromatic poly-phc----		0.1284	2.50%	25000	14330
				C	1333-86-4	0.0103	0.20%	2000	1146
		Die attached epoxy	84-1 LMISR4	Ag	7440-22-4	0.1542	75.00%	750000	17206
				epoxy resin	Trade secret	0.0411	20.00%	200000	4588
				curing agent & hardener	Trade secret	0.0103	5.00%	50000	1147
		Tin solder	Pure Tin	Sn	7440-31-5	0.2555	100.00%	1000000	28514
Total (mg)						8.959			